Lattice Semiconductor Corporation - LCMXO1200C-4B256C Datasheet

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Details	
Product Status	Obsolete
Number of LABs/CLBs	150
Number of Logic Elements/Cells	1200
Total RAM Bits	9421
Number of I/O	211
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LFBGA, CSPBGA
Supplier Device Package	256-CABGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo1200c-4b256c

MachXO Family Data Sheet Architecture

June 2013 Data Sheet DS1002

Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT use.

The MachXO registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM, and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables (LUT4). A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7, and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
  - A greater-than-or-equal-to B
  - A not-equal-to B
  - A less-than-or-equal-to B

Two additional signals, Carry Generate and Carry Propagate, are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x2-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

The ispLEVER design tool supports the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-6 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices. One Slice functions as the read-write port, while the other companion Slice supports the read-only port. For more information on RAM mode in MachXO devices, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

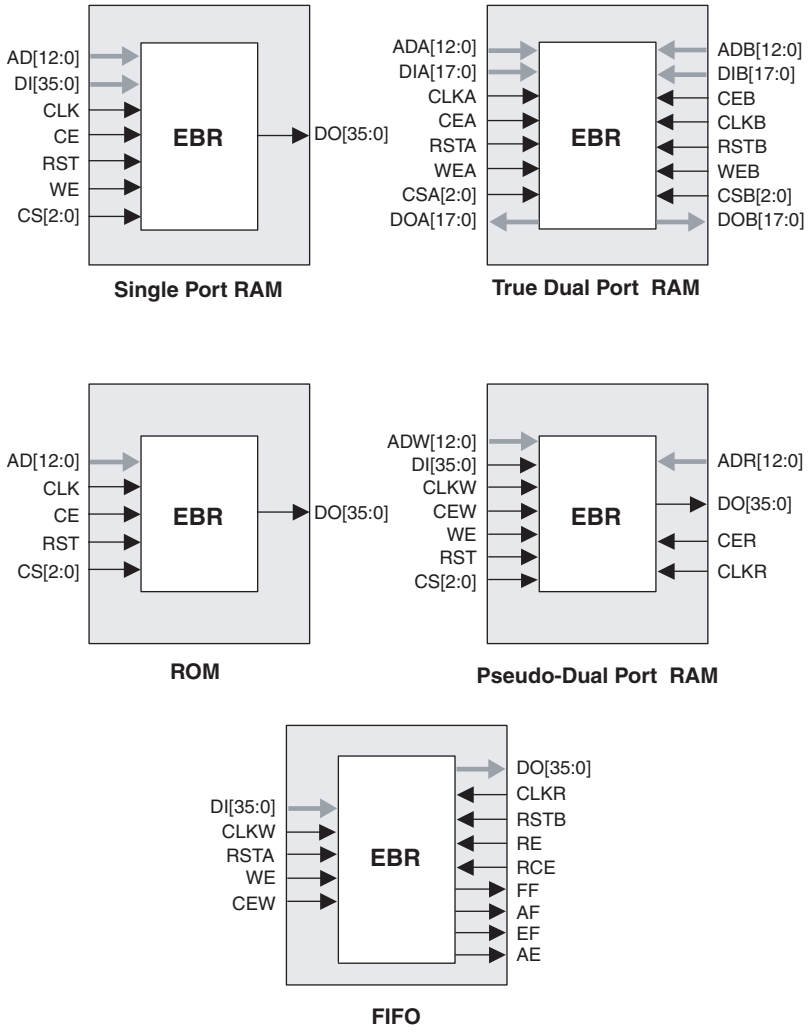
Memory Cascading

Larger and deeper blocks of RAMs can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual, Pseudo-Dual Port and FIFO Modes

Figure 2-12 shows the five basic memory configurations and their input/output names. In all the sysMEM RAM modes, the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the memory array output.

Figure 2-12. sysMEM Memory Primitives



The EBR memory supports three forms of write behavior for single or dual port operation:

1. **Normal** – data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

2. **Write Through** – a copy of the input data appears at the output of the same port. This mode is supported for all data widths.

3. **Read-Before-Write** – when new data is being written, the old contents of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

FIFO Configuration

The FIFO has a write port with Data-in, CEW, WE and CLKW signals. There is a separate read port with Data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. The range of programming values for these flags are in Table 2-7.

Table 2-7. Programmable FIFO Flag Ranges

Flag Name	Programming Range
Full (FF)	1 to (up to 2^N-1)
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

N = Address bit width

The FIFO state machine supports two types of reset signals: RSTA and RSTB. The RSTA signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RSTB signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-13.

of the devices also support differential input buffers. PCI clamps are available on the top Bank I/O buffers. The PCI clamp is enabled after V_{CC}, V_{CCAUX}, and V_{CCIO} are at valid operating levels and the device has been configured.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

2. **Left and Right sysIO Buffer Pairs**
The sysIO buffer pairs in the left and right Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (supporting ratioed and absolute input levels). The devices also have a differential driver per output pair. The referenced input buffer can also be configured as a differential input buffer. In these Banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user’s responsibility to ensure that all V_{CCIO} Banks are active with valid input logic levels to properly control the output logic states of all the I/O Banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to VCCIO. The I/O pins will maintain the blank configuration until VCC, VCCAUX and VCCIO have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, the I/O buffers should be powered up along with the FPGA core fabric. Therefore, V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies

Supported Standards

The MachXO sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS and LVTTL. The buffer supports the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5, and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, bus-keeper latch or none) and open drain. BLVDS and LVPECL output emulation is supported on all devices. The MachXO1200 and MachXO2280 support on-chip LVDS output buffers on approximately 50% of the I/Os on the left and right Banks. Differential receivers for LVDS, BLVDS and LVPECL are supported on all Banks of MachXO1200 and MachXO2280 devices. PCI support is provided in the top Banks of the MachXO1200 and MachXO2280 devices. Table 2-8 summarizes the I/O characteristics of the devices in the MachXO family.

Tables 2-9 and 2-10 show the I/O standards (together with their supply and reference voltages) supported by the MachXO devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Figure 2-18. MachXO2280 Banks

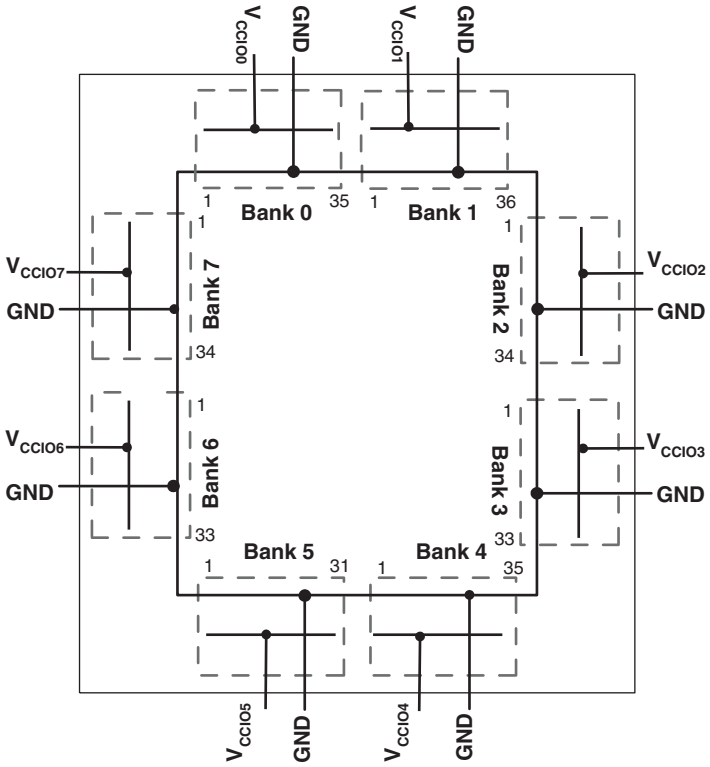
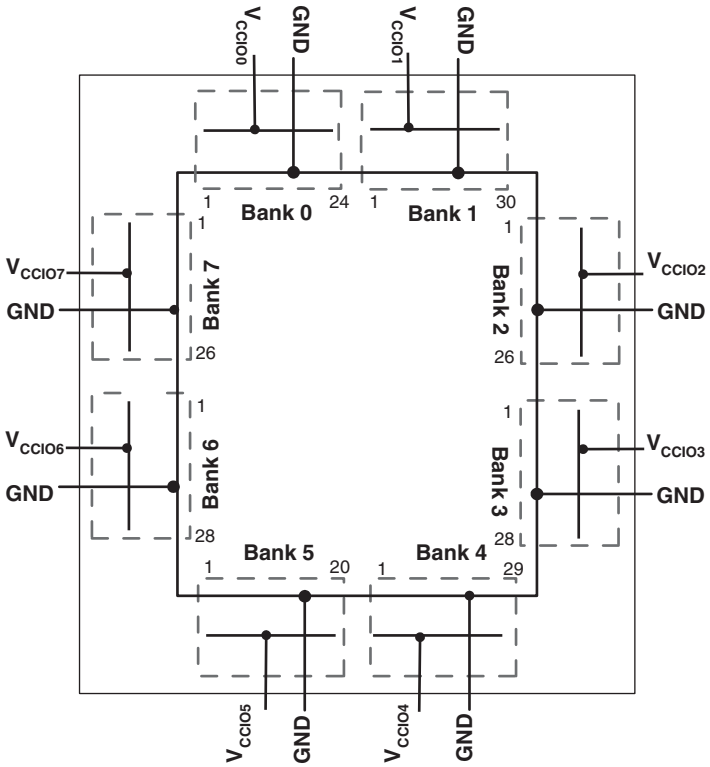


Figure 2-19. MachXO1200 Banks



Absolute Maximum Ratings[1, 2, 3]

	LCMXO E (1.2V)	LCMXO C (1.8V/2.5V/3.3V)
Supply Voltage V_{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied [4]	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied[4]	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (ambient)	-65 to 150°C	-65 to 150°C
Junction Temp. (Tj)	+125°C	+125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[1]

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCAUX}[3]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCIO}[2]	I/O Driver Supply Voltage	1.14	3.465	V
t_{JCOM}	Junction Temperature Commercial Operation	0	+85	°C
t_{JIND}	Junction Temperature Industrial Operation	-40	100	°C
$t_{JFLASHCOM}$	Junction Temperature, Flash Programming, Commercial	0	+85	°C
$t_{JFLASHIND}$	Junction Temperature, Flash Programming, Industrial	-40	100	°C

1. Like power supplies must be tied together. For example, if V_{CCIO} and V_{CC} are both 2.5V, they must also be the same supply. 3.3V V_{CCIO} and 1.2V V_{CCIO} should be tied to V_{CCAUX} or 1.2V V_{CC} respectively.
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CC} must reach minimum V_{CC} value before V_{CCAUX} reaches 2.5V.

MachXO Programming/Erase Specifications

Symbol	Parameter	Min.	Max.	Units
$N_{PROGCYC}$	Flash Programming Cycles per $t_{RETENTION}$		1,000	Cycles
	Flash Functional Programming Cycles		10,000	Cycles
$t_{RETENTION}$	Data Retention at 125° Junction Temperature	10		Years

Initialization Supply Current[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO256C	13	mA
		LCMXO640C	17	mA
		LCMXO1200C	21	mA
		LCMXO2280C	23	mA
		LCMXO256E	10	mA
		LCMXO640E	14	mA
		LCMXO1200E	18	mA
		LCMXO2280E	20	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LCMXO256E/C	10	mA
		LCMXO640E/C	13	mA
		LCMXO1200E/C	24	mA
		LCMXO2280E/C	25	mA
I_{CCIO}	Bank Power Supply[6]	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all I/O pins are held at V_{CCIO} or GND.
3. Frequency = 0MHz.
4. Typical user pattern.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank, V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

Programming and Erase Flash Supply Current[1, 2, 3, 4]

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply	LCMXO256C	9	mA
		LCMXO640C	11	mA
		LCMXO1200C	16	mA
		LCMXO2280C	22	mA
		LCMXO256E	6	mA
		LCMXO640E	8	mA
		LCMXO1200E	12	mA
		LCMXO2280E	14	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LCMXO256C/E	8	mA
		LCMXO640C/E	10	mA
		LCMXO1200/E	15	mA
		LCMXO2280C/E	16	mA
I_{CCIO}	Bank Power Supply[6]	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all I/O pins are held at V_{CCIO} or GND.
3. Typical user pattern.
4. JTAG programming is at 25MHz.
5. T_J = 25°C, power supplies at nominal voltage.
6. Per Bank. V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

MachXO Family Timing Adders[1, 2, 3]

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25[4]	LVDS	0.44	0.53	0.61	ns
BLVDS25[4]	BLVDS	0.44	0.53	0.61	ns
LVPECL33[4]	LVPECL	0.42	0.50	0.59	ns
LVTTL33	LVTTL	0.01	0.01	0.01	ns
LVCMOS33	LVCMOS 3.3	0.01	0.01	0.01	ns
LVCMOS25	LVCMOS 2.5	0.00	0.00	0.00	ns
LVCMOS18	LVCMOS 1.8	0.07	0.08	0.10	ns
LVCMOS15	LVCMOS 1.5	0.14	0.17	0.19	ns
LVCMOS12	LVCMOS 1.2	0.40	0.48	0.56	ns
PCI33[4]	PCI	0.01	0.01	0.01	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25[4]	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTL33_4mA	LVTTL 4mA drive	0.04	0.04	0.05	ns
LVTTL33_8mA	LVTTL 8mA drive	0.06	0.07	0.08	ns
LVTTL33_12mA	LVTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTL33_16mA	LVTTL 16mA drive	0.50	0.60	0.70	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVCMOS33_14mA	LVCMOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVCMOS25_14mA	LVCMOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVCMOS18_14mA	LVCMOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33[4]	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.
2. LVCMOS timing is measured with the load specified in Switching Test Conditions table.
3. All other standards tested according to the appropriate specifications.
4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.

Rev. A 0.19

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Descriptions	Conditions	Min.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		25	420	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4[5, 6]	18	25	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	420	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	210	MHz
f_{VCO}	PLL VCO Frequency		420	840	MHz
f_{PFD}	Phase Detector Input Frequency		25	—	MHz
		Input Divider (M) = 1; Feedback Divider (N) <= 4[5, 6]	18	25	MHz
AC Characteristics					
t_{DT}	Output Clock Duty Cycle	Default duty cycle selected[3]	45	55	%
t_{PH}[4]	Output Phase Accuracy		—	0.05	UI
t_{OPJIT}[1]	Output Clock Period Jitter	f_{OUT} >= 100 MHz	—	+/-120	ps
		f_{OUT} < 100 MHz	—	0.02	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	+/-200	ps
t_W	Output Clock Pulse Width	At 90% or 10%[3]	1	—	ns
t_{LOCK}[2]	PLL Lock-in Time		—	150	µs
t_{PA}	Programmable Delay Unit		100	450	ps
t_{IPJIT}	Input Clock Period Jitter	$f_{OUT} \geq$ 100 MHz	—	+/-200	ps
		f_{OUT} < 100 MHz	—	0.02	UI
t_{FBKDLY}	External Feedback Delay		—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	ns
t_{RST}	RST Pulse Width		10	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with a clean reference clock.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. CLKOS as compared to CLKOP output.
5. When using an input frequency less than 25 MHz the output frequency must be less than or equal to 4 times the input frequency.
6. The on-chip oscillator can be used to provide reference clock input to the PLL provided the output frequency restriction for clock inputs below 25 MHz are followed.

Rev. A 0.19

LCMXO256 and LCMXO640 Logic Signal Connections: 100 TQFP

Pin Number	LCMXO256				LCMXO640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	1		T	PL2A	3		T
2	PL2B	1		C	PL2C	3		T
3	PL3A	1		T	PL2B	3		C
4	PL3B	1		C	PL2D	3		C
5	PL3C	1		T	PL3A	3		T
6	PL3D	1		C	PL3B	3		C
7	PL4A	1		T	PL3C	3		T
8	PL4B	1		C	PL3D	3		C
9	PL5A	1		T	PL4A	3		
10	VCCIO1	1			VCCIO3	3		
11	PL5B	1		C	PL4C	3		T
12	GNDIO1	1			GNDIO3	3		
13	PL5C	1		T	PL4D	3		C
14	PL5D	1	GSRN	C	PL5B	3	GSRN	
15	PL6A	1		T	PL7B	3		
16	PL6B	1	TSALL	C	PL8C	3	TSALL	T
17	PL7A	1		T	PL8D	3		C
18	PL7B	1		C	PL9A	3		
19	PL7C	1		T	PL9C	3		
20	PL7D	1		C	PL10A	3		
21	PL8A	1		T	PL10C	3		
22	PL8B	1		C	PL11A	3		
23	PL9A	1		T	PL11C	3		
24	VCCIO1	1			VCCIO3	3		
25	GNDIO1	1			GNDIO3	3		
26	TMS	1	TMS		TMS	2	TMS	
27	PL9B	1		C	PB2C	2		
28	TCK	1	TCK		TCK	2	TCK	
29	PB2A	1		T	VCCIO2	2		
30	PB2B	1		C	GNDIO2	2		
31	TDO	1	TDO		TDO	2	TDO	
32	PB2C	1		T	PB4C	2		
33	TDI	1	TDI		TDI	2	TDI	
34	PB2D	1		C	PB4E	2		
35	VCC	-			VCC	-		
36	PB3A	1	PCLK1_1**	T	PB5B	2	PCLK2_1**	
37	PB3B	1		C	PB5D	2		
38	PB3C	1	PCLK1_0**	T	PB6B	2	PCLK2_0**	
39	PB3D	1		C	PB6C	2		
40	GND	-			GND	-		
41	VCCIO1	1			VCCIO2	2		
42	GNDIO1	1			GNDIO2	2		

LCMXO1200 and LCMXO2280 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
42	PB9A	4		T	PB12A	4		T
43	PB9B	4		C	PB12B	4		C
44	VCCIO4	4			VCCIO4	4		
45	PB10A	4		T	PB13A	4		T
46	PB10B	4		C	PB13B	4		C
47***	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
48	PB11A	4		T	PB16A	4		T
49	PB11B	4		C	PB16B	4		C
50**	GNDIO3 GNDIO4	-			GNDIO3 GNDIO4	-		
51	PR16B	3			PR19B	3		
52	PR15B	3		C*	PR18B	3		C*
53	PR15A	3		T*	PR18A	3		T*
54	PR14B	3		C*	PR17B	3		C*
55	PR14A	3		T*	PR17A	3		T*
56	VCCIO3	3			VCCIO3	3		
57	PR12B	3		C*	PR15B	3		C*
58	PR12A	3		T*	PR15A	3		T*
59	GND	-			GND	-		
60	PR10B	3		C*	PR13B	3		C*
61	PR10A	3		T*	PR13A	3		T*
62	PR9B	3		C*	PR11B	3		C*
63	PR9A	3		T*	PR11A	3		T*
64	PR8B	2		C*	PR10B	2		C*
65	PR8A	2		T*	PR10A	2		T*
66	VCC	-			VCC	-		
67	PR6C	2			PR8C	2		
68	PR6B	2		C*	PR8B	2		C*
69	PR6A	2		T*	PR8A	2		T*
70	VCCIO2	2			VCCIO2	2		
71	PR4D	2			PR5D	2		
72	PR4B	2		C*	PR5B	2		C*
73	PR4A	2		T*	PR5A	2		T*
74	PR2B	2		C	PR3B	2		C*
75	PR2A	2		T	PR3A	2		T*
76**	GNDIO1 GNDIO2	-			GNDIO1 GNDIO2	-		
77	PT11C	1			PT15C	1		
78	PT11B	1		C	PT14B	1		C
79	PT11A	1		T	PT14A	1		T
80	VCCIO1	1			VCCIO1	1		
81	PT9E	1			PT12D	1		C

LCMXO256 and LCMXO640 Logic Signal Connections: 100 csBGA

LCMXO256					LCMXO640				
Ball Number	Ball Function	Bank	Dual Function	Differen-tial	Ball Number	Ball Function	Bank	Dual Function	Differen-tial
B1	PL2A	1		T	B1	PL2A	3		T
C1	PL2B	1		C	C1	PL2C	3		T
D2	PL3A	1		T	D2	PL2B	3		C
D1	PL3B	1		C	D1	PL2D	3		C
C2	PL3C	1		T	C2	PL3A	3		T
E1	PL3D	1		C	E1	PL3B	3		C
E2	PL4A	1		T	E2	PL3C	3		T
F1	PL4B	1		C	F1	PL3D	3		C
F2	PL5A	1		T	F2	PL4A	3		
G2	PL5B	1		C	G2	PL4C	3		T
H1	GNDIO1	1			H1	GNDIO3	3		
H2	PL5C	1		T	H2	PL4D	3		C
J1	PL5D	1	GSRN	C	J1	PL5B	3	GSRN	
J2	PL6A	1		T	J2	PL7B	3		
K1	PL6B	1	TSALL	C	K1	PL8C	3	TSALL	T
K2	PL7A	1		T	K2	PL8D	3		C
L1	PL7B	1		C	L1	PL9A	3		
L2	PL7C	1		T	L2	PL9C	3		
M1	PL7D	1		C	M1	PL10A	3		
M2	PL8A	1		T	M2	PL10C	3		
N1	PL8B	1		C	N1	PL11A	3		
M3	PL9A	1		T	M3	PL11C	3		
N2	GNDIO1	1			N2	GNDIO3	3		
P2	TMS	1	TMS		P2	TMS	2	TMS	
P3	PL9B	1		C	P3	PB2C	2		
N4	TCK	1	TCK		N4	TCK	2	TCK	
P4	PB2A	1		T	P4	VCCIO2	2		
N3	PB2B	1		C	N3	GNDIO2	2		
P5	TDO	1	TDO		P5	TDO	2	TDO	
N5	PB2C	1		T	N5	PB4C	2		
P6	TDI	1	TDI		P6	TDI	2	TDI	
N6	PB2D	1		C	N6	PB4E	2		
P7	VCC	-			P7	VCC	-		
N7	PB3A	1	PCLK1_1**	T	N7	PB5B	2	PCLK2_1**	
P8	PB3B	1		C	P8	PB5D	2		
N8	PB3C	1	PCLK1_0**	T	N8	PB6B	2	PCLK2_0**	
P9	PB3D	1		C	P9	PB6C	2		
N10	GNDIO1	1			N10	GNDIO2	2		
P11	PB4A	1		T	P11	PB8B	2		
N11	PB4B	1		C	N11	PB8C	2		T
P12	PB4C	1		T	P12	PB8D	2		C
N12	PB4D	1		C	N12	PB9A	2		

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J4	PL8A	3		T	J4	PL13A	6		T*	J4	PL16A	6		T*
J5	PL8B	3		C	J5	PL13B	6		C*	J5	PL16B	6		C*
R1	PL11A	3		T	R1	PL13C	6		T	R1	PL16C	6		T
R2	PL11B	3		C	R2	PL13D	6		C	R2	PL16D	6		C
-	-	-			-	-	-			GND	GND	-		
K5	NC				K5	PL14A	6	LLM0_PLLT_FB_A	T*	K5	PL17A	6	LLM0_PLLT_FB_A	T*
K4	NC				K4	PL14B	6	LLM0_PLLC_FB_A	C*	K4	PL17B	6	LLM0_PLLC_FB_A	C*
L5	PL10C	3		T	L5	PL14C	6		T	L5	PL17C	6		T
L4	PL10D	3		C	L4	PL14D	6		C	L4	PL17D	6		C
M5	NC				M5	PL15A	6	LLM0_PLLT_IN_A	T*	M5	PL18A	6	LLM0_PLLT_IN_A	T*
M4	NC				M4	PL15B	6	LLM0_PLLC_IN_A	C*	M4	PL18B	6	LLM0_PLLC_IN_A	C*
N4	PL11C	3		T	N4	PL16A	6		T	N4	PL19A	6		T
N3	PL11D	3		C	N3	PL16B	6		C	N3	PL19B	6		C
VCCIO3	VCCIO3	3			VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
GND	GNDIO3	3			GND	GNDIO6	6			GND	GNDIO6	6		
GND	GNDIO2	2			GND	GNDIO5	5			GND	GNDIO5	5		
VCCIO2	VCCIO2	2			VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
P4	TMS	2	TMS		P4	TMS	5	TMS		P4	TMS	5	TMS	
P2	NC				P2	PB2A	5		T	P2	PB2A	5		T
P3	NC				P3	PB2B	5		C	P3	PB2B	5		C
N5	NC				N5	PB2C	5		T	N5	PB2C	5		T
R3	TCK	2	TCK		R3	TCK	5	TCK		R3	TCK	5	TCK	
N6	NC				N6	PB2D	5		C	N6	PB2D	5		C
T2	PB2A	2		T	T2	PB3A	5		T	T2	PB3A	5		T
T3	PB2B	2		C	T3	PB3B	5		C	T3	PB3B	5		C
R4	PB2C	2		T	R4	PB3C	5		T	R4	PB3C	5		T
R5	PB2D	2		C	R5	PB3D	5		C	R5	PB3D	5		C
P5	PB3A	2		T	P5	PB4A	5		T	P5	PB4A	5		T
P6	PB3B	2		C	P6	PB4B	5		C	P6	PB4B	5		C
T5	PB3C	2		T	T5	PB4C	5		T	T5	PB4C	5		T
M6	TDO	2	TDO		M6	TDO	5	TDO		M6	TDO	5	TDO	
T4	PB3D	2		C	T4	PB4D	5		C	T4	PB4D	5		C
R6	PB4A	2		T	R6	PB5A	5		T	R6	PB5A	5		T
GND	GNDIO2	2			GND	GNDIO5	5			GND	GNDIO5	5		
VCCIO2	VCCIO2	2			VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
T6	PB4B	2		C	T6	PB5B	5		C	T6	PB5B	5		C
N7	TDI	2	TDI		N7	TDI	5	TDI		N7	TDI	5	TDI	
T8	PB4C	2		T	T8	PB5C	5		T	T8	PB6A	5		T
T7	PB4D	2		C	T7	PB5D	5		C	T7	PB6B	5		C
M7	NC				M7	PB6A	5		T	M7	PB7C	5		T
M8	NC				M8	PB6B	5		C	M8	PB7D	5		C
T9	VCCAUX	-			T9	VCCAUX	-			T9	VCCAUX	-		
R7	PB4E	2		T	R7	PB6C	5		T	R7	PB8C	5		T
R8	PB4F	2		C	R8	PB6D	5		C	R8	PB8D	5		C
-	-				VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
-	-				GND	GNDIO5	5			GND	GNDIO5	5		
P7	PB5C	2		T	P7	PB6E	5		T	P7	PB9A	4		T
P8	PB5D	2		C	P8	PB6F	5		C	P8	PB9B	4		C
N8	PB5A	2		T	N8	PB7A	4		T	N8	PB10E	4		T
N9	PB5B	2	PCLK2_1***	C	N9	PB7B	4	PCLK4_1***	C	N9	PB10F	4	PCLK4_1***	C
P10	PB7B	2		C	P10	PB7D	4		C	P10	PB10D	4		C
P9	PB7A	2		T	P9	PB7C	4		T	P9	PB10C	4		T
M9	PB6B	2	PCLK2_0***	C	M9	PB7F	4	PCLK4_0***	C	M9	PB10B	4	PCLK4_0***	C

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
G2	PL11A	6		T*
H2	PL11B	6		C*
L3	PL11C	6		T
L5	PL11D	6		C
H1	PL12A	6		T*
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
J2	PL12B	6		C*
L4	PL12C	6		T
L6	PL12D	6		C
K2	PL13A	6		T*
K1	PL13B	6		C*
J1	PL13C	6		T
VCC	VCC	-		
L2	PL13D	6		C
M5	PL14D	6		C
M3	PL14C	6	TSALL	T
L1	PL14B	6		C*
M2	PL14A	6		T*
M1	PL15A	6		T*
N1	PL15B	6		C*
M6	PL15C	6		T
M4	PL15D	6		C
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
P1	PL16A	6		T*
P2	PL16B	6		C*
N3	PL16C	6		T
N4	PL16D	6		C
GND	GND	-		
T1	PL17A	6	LLM0_PLLT_FB_A	T*
R1	PL17B	6	LLM0_PLLC_FB_A	C*
P3	PL17C	6		T
N5	PL17D	6		C
R3	PL18A	6	LLM0_PLLT_IN_A	T*
R2	PL18B	6	LLM0_PLLC_IN_A	C*
P4	PL19A	6		T
N6	PL19B	6		C
U1	PL20A	6		T
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
GND	GNDIO5	5		
VCCIO5	VCCIO5	5		

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
P15	PR20B	3		C
N14	PR20A	3		T
N15	PR19B	3		C
M13	PR19A	3		T
R15	PR18B	3		C*
T16	PR18A	3		T*
N16	PR17D	3		C
M14	PR17C	3		T
U17	PR17B	3		C*
VCC	VCC	-		
U18	PR17A	3		T*
R17	PR16D	3		C
R16	PR16C	3		T
P16	PR16B	3		C*
VCCIO3	VCCIO3	3		
GND	GNDIO3	3		
P17	PR16A	3		T*
L13	PR15D	3		C
M15	PR15C	3		T
T17	PR15B	3		C*
T18	PR15A	3		T*
L14	PR14D	3		C
L15	PR14C	3		T
R18	PR14B	3		C*
P18	PR14A	3		T*
GND	GND	-		
K15	PR13D	3		C
K13	PR13C	3		T
N17	PR13B	3		C*
N18	PR13A	3		T*
K16	PR12D	3		C
K14	PR12C	3		T
M16	PR12B	3		C*
L16	PR12A	3		T*
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
J16	PR11D	3		C
J14	PR11C	3		T
M17	PR11B	3		C*
L17	PR11A	3		T*
J15	PR10D	2		C

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
A10	PT8E	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
A9	PT8D	0		C
C9	PT8C	0		T
B9	PT8B	0		C
F9	VCCAUX	-		
A8	PT8A	0		T
B8	PT7D	0		C
C8	PT7C	0		T
VCC	VCC	-		
A7	PT7B	0		C
B7	PT7A	0		T
A6	PT6A	0		T
B6	PT6B	0		C
D8	PT6C	0		T
F8	PT6D	0		C
C7	PT6E	0		T
E8	PT6F	0		C
D7	PT5D	0		C
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E7	PT5C	0		T
A5	PT5B	0		C
C6	PT5A	0		T
B5	PT4A	0		T
A4	PT4B	0		C
D6	PT4C	0		T
F7	PT4D	0		C
B4	PT4E	0		T
GND	GND	-		
C5	PT4F	0		C
F6	PT3D	0		C
E5	PT3C	0		T
E6	PT3B	0		C
D5	PT3A	0		T
A3	PT2D	0		C
C4	PT2C	0		T
A2	PT2B	0		C
B2	PT2A	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E14	GND	-		

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
F16	GND	-		
H10	GND	-		
H11	GND	-		
H8	GND	-		
H9	GND	-		
J10	GND	-		
J11	GND	-		
J4	GND	-		
J8	GND	-		
J9	GND	-		
K10	GND	-		
K11	GND	-		
K17	GND	-		
K8	GND	-		
K9	GND	-		
L10	GND	-		
L11	GND	-		
L8	GND	-		
L9	GND	-		
N2	GND	-		
P14	GND	-		
P5	GND	-		
R7	GND	-		
F14	VCC	-		
G11	VCC	-		
G9	VCC	-		
H7	VCC	-		
L7	VCC	-		
M9	VCC	-		
H6	VCCIO7	7		
J7	VCCIO7	7		
M7	VCCIO6	6		
K7	VCCIO6	6		
M8	VCCIO5	5		
R9	VCCIO5	5		
M12	VCCIO4	4		
M11	VCCIO4	4		
L12	VCCIO3	3		
K12	VCCIO3	3		
J12	VCCIO2	2		
H12	VCCIO2	2		
G12	VCCIO1	1		
G10	VCCIO1	1		

Conventional Packaging

Industrial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256C-3T100I	256	1.8V/2.5V/3.3V	78	-3	TQFP	100	IND
LCMXO256C-4T100I	256	1.8V/2.5V/3.3V	78	-4	TQFP	100	IND
LCMXO256C-3M100I	256	1.8V/2.5V/3.3V	78	-3	csBGA	100	IND
LCMXO256C-4M100I	256	1.8V/2.5V/3.3V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640C-3T100I	640	1.8V/2.5V/3.3V	74	-3	TQFP	100	IND
LCMXO640C-4T100I	640	1.8V/2.5V/3.3V	74	-4	TQFP	100	IND
LCMXO640C-3M100I	640	1.8V/2.5V/3.3V	74	-3	csBGA	100	IND
LCMXO640C-4M100I	640	1.8V/2.5V/3.3V	74	-4	csBGA	100	IND
LCMXO640C-3T144I	640	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMXO640C-4T144I	640	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMXO640C-3M132I	640	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMXO640C-4M132I	640	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMXO640C-3B256I	640	1.8V/2.5V/3.3V	159	-3	caBGA	256	IND
LCMXO640C-4B256I	640	1.8V/2.5V/3.3V	159	-4	caBGA	256	IND
LCMXO640C-3FT256I	640	1.8V/2.5V/3.3V	159	-3	ftBGA	256	IND
LCMXO640C-4FT256I	640	1.8V/2.5V/3.3V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200C-3T100I	1200	1.8V/2.5V/3.3V	73	-3	TQFP	100	IND
LCMXO1200C-4T100I	1200	1.8V/2.5V/3.3V	73	-4	TQFP	100	IND
LCMXO1200C-3T144I	1200	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMXO1200C-4T144I	1200	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMXO1200C-3M132I	1200	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMXO1200C-4M132I	1200	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMXO1200C-3B256I	1200	1.8V/2.5V/3.3V	211	-3	caBGA	256	IND
LCMXO1200C-4B256I	1200	1.8V/2.5V/3.3V	211	-4	caBGA	256	IND
LCMXO1200C-3FT256I	1200	1.8V/2.5V/3.3V	211	-3	ftBGA	256	IND
LCMXO1200C-4FT256I	1200	1.8V/2.5V/3.3V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280C-3T100I	2280	1.8V/2.5V/3.3V	73	-3	TQFP	100	IND
LCMXO2280C-4T100I	2280	1.8V/2.5V/3.3V	73	-4	TQFP	100	IND
LCMXO2280C-3T144I	2280	1.8V/2.5V/3.3V	113	-3	TQFP	144	IND
LCMXO2280C-4T144I	2280	1.8V/2.5V/3.3V	113	-4	TQFP	144	IND
LCMXO2280C-3M132I	2280	1.8V/2.5V/3.3V	101	-3	csBGA	132	IND
LCMXO2280C-4M132I	2280	1.8V/2.5V/3.3V	101	-4	csBGA	132	IND
LCMXO2280C-3B256I	2280	1.8V/2.5V/3.3V	211	-3	caBGA	256	IND
LCMXO2280C-4B256I	2280	1.8V/2.5V/3.3V	211	-4	caBGA	256	IND
LCMXO2280C-3FT256I	2280	1.8V/2.5V/3.3V	211	-3	ftBGA	256	IND
LCMXO2280C-4FT256I	2280	1.8V/2.5V/3.3V	211	-4	ftBGA	256	IND
LCMXO2280C-3FT324I	2280	1.8V/2.5V/3.3V	271	-3	ftBGA	324	IND
LCMXO2280C-4FT324I	2280	1.8V/2.5V/3.3V	271	-4	ftBGA	324	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3TN100C	1200	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMXO1200E-4TN100C	1200	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMXO1200E-5TN100C	1200	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMXO1200E-3TN144C	1200	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMXO1200E-4TN144C	1200	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMXO1200E-5TN144C	1200	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMXO1200E-3MN132C	1200	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMXO1200E-4MN132C	1200	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMXO1200E-5MN132C	1200	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMXO1200E-3BN256C	1200	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMXO1200E-4BN256C	1200	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMXO1200E-5BN256C	1200	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMXO1200E-3FTN256C	1200	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMXO1200E-4FTN256C	1200	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMXO1200E-5FTN256C	1200	1.2V	211	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3TN100C	2280	1.2V	73	-3	Lead-Free TQFP	100	COM
LCMXO2280E-4TN100C	2280	1.2V	73	-4	Lead-Free TQFP	100	COM
LCMXO2280E-5TN100C	2280	1.2V	73	-5	Lead-Free TQFP	100	COM
LCMXO2280E-3TN144C	2280	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMXO2280E-4TN144C	2280	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMXO2280E-5TN144C	2280	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMXO2280E-3MN132C	2280	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMXO2280E-4MN132C	2280	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMXO2280E-5MN132C	2280	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMXO2280E-3BN256C	2280	1.2V	211	-3	Lead-Free caBGA	256	COM
LCMXO2280E-4BN256C	2280	1.2V	211	-4	Lead-Free caBGA	256	COM
LCMXO2280E-5BN256C	2280	1.2V	211	-5	Lead-Free caBGA	256	COM
LCMXO2280E-3FTN256C	2280	1.2V	211	-3	Lead-Free ftBGA	256	COM
LCMXO2280E-4FTN256C	2280	1.2V	211	-4	Lead-Free ftBGA	256	COM
LCMXO2280E-5FTN256C	2280	1.2V	211	-5	Lead-Free ftBGA	256	COM
LCMXO2280E-3FTN324C	2280	1.2V	271	-3	Lead-Free ftBGA	324	COM
LCMXO2280E-4FTN324C	2280	1.2V	271	-4	Lead-Free ftBGA	324	COM
LCMXO2280E-5FTN324C	2280	1.2V	271	-5	Lead-Free ftBGA	324	COM